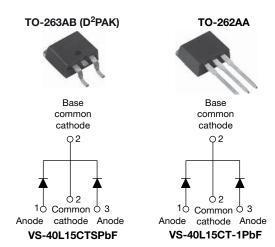


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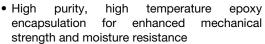
High Performance Schottky Rectifier, 2 x 20 A



PRODUCT SUMMARY	
Package	TO-263AB (D ² PAK), TO-262AA
I _{F(AV)}	2 x 20 A
V_{R}	15 V
V _F at I _F	see datasheet
I _{RM} max.	600 mA at 100 °C
T _J max.	125 °C
E _{AS}	10 mJ
Diode variation	Common cathode

FEATURES

- 125 °C T_J operation (V_R < 5 V)
- Center tap module
- · Optimized for OR-ing applications
- Ultralow forward voltage drop
- High frequency operation





- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION

The center tap Schottky rectifier module has been optimized for ultralow forward voltage drop specifically for the OR-ing of parallel power supplies. The proprietary barrier technology allows for reliable operation up to 125 °C junction temperature. Typical applications are in parallel switching power supplies, converters, reverse battery protection, and redundant power subsystems.

MAJOR RATINGS AND CHARACTERISTICS				
SYMBOL	CHARACTERISTICS	VALUES	UNITS	
I _{F(AV)}	Rectangular waveform	40	Α	
V_{RRM}		15	V	
I _{FSM}	t _p = 5 μs sine	700	Α	
V _F	19 A _{pk} , T _J = 125 °C (per leg, typical)	0.25	V	
T _J		-55 to +125	°C	

VOLTAGE RATINGS					
PARAMETER SYMBOL TEST CONDITIONS VS-40L15CTSPbF VS-40L15CT-1PbF UNITS					
Maximum DC reverse voltage	V_{R}	T.ı = 100 °C	15	V	
Maximum working peak reverse voltage	V_{RWM}	1 1 = 100 C	15	V	

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST COND	ITIONS	VALUES	UNITS
Maximum average forward per leg	1	I _{F(AV)} 50 % duty cycle at T _C = 85 °C, rectangular waveform		20	
current, see fig. 5 per device	F(AV)			40	
Maximum peak one cycle non-repetitive		5 μs sine or 3 μs rect. pulse		Α	
surge current per leg, see fig. 7	IFSM	10 ms sine or 6 ms rect. pulse	condition and with rated V _{RRM} applied	330	
Non-repetitive avalanche energy per leg	E _{AS}	$T_J = 25 ^{\circ}\text{C}, I_{AS} = 2 \text{A}, L = 6 \text{mH}$		10	mJ
Repetitive avalanche current per leg	I _{AR}	Current decaying linearly to zero Frequency limited by T _J maximu		2	Α



VS-40L15CTSPbF, VS-40L15CT-1PbF

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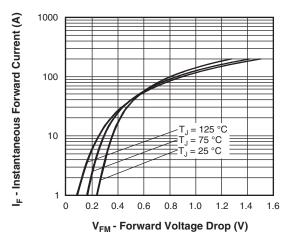
ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CO	NDITIONS	TYP.	MAX.	UNITS
		19 A	T _{.1} = 25 °C	1	0.41	
Maximum forward voltage drop per leg See fig. 1	V _{FM} ⁽¹⁾	40 A	1j=25 C	-	0.52	v
	VFM (1)	19 A	T _{.1} = 125 °C	0.25	0.33	\ \ \
		40 A	1j = 125 C	0.37	0.50	
Reverse leakage current per leg	I _{RM} ⁽¹⁾	T _J = 25 °C	V _R = Rated V _R	-	10	mA
See fig. 2	IRM ('')	T _J = 100 °C	V _R = nateu V _R	-	600	IIIA
Threshold voltage	V _{F(TO)}	T T mayimum		0.1	82	V
Forward slope resistance	r _t	$T_J = T_J$ maximum		7	.6	mΩ
Maximum junction capacitance per leg	C _T	V _R = 5 V _{DC} (test signal range	ge 100 kHz to 1 MHz), 25 °C	-	2000	pF
Typical series inductance per leg	L _S	Measured lead to lead 5 mm from package body 8		-	nH	
Maximum voltage rate of change	dV/dt	Rated V _R		10	000	V/µs

Note

 $^{(1)}\,$ Pulse width < 300 $\mu s,$ duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction temperature range		T_J		-55 to +125	°C
Maximum storage temperat	ure range	T _{Stg}		-55 to +150	C
Maximum thermal resistance, junction to case per leg		R _{thJC}	DC operation See fig. 4	1.5	
Typical thermal resistance, case to heatsink		R _{thCS}	Mounting surface, smooth and greased	0.50	°C/W
Maximum thermal resistance, junction to ambient		R _{thJA}	DC operation	40	
Approximate weight				2	g
Approximate weight				0.07	oz.
Mounting torque	minimum		Non-lubricated threads	6 (5)	kgf · cm
Mounting torque maximum			Non-lubricated tilleads	12 (10)	(lbf · in)
Marking daviso			Case style TO-263AB (D ² PAK)	40L1	5CTS
Marking device			Case style TO-262AA	40L1	SCT-1

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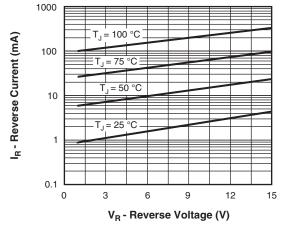


Fig. 1 - Maximum Forward Voltage Drop Characteristics

Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

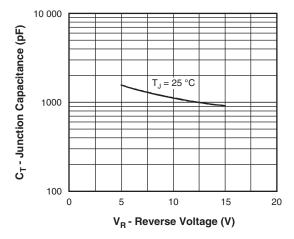


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

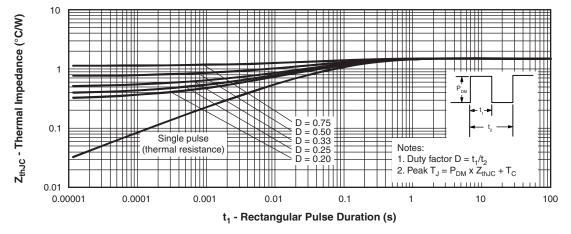


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

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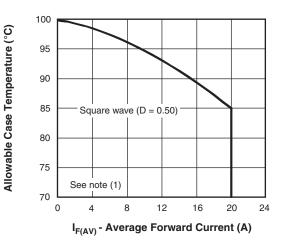


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

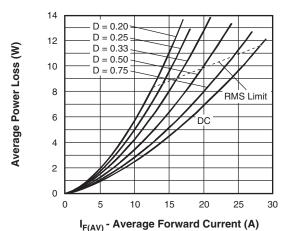


Fig. 6 - Forward Power Loss Characteristics

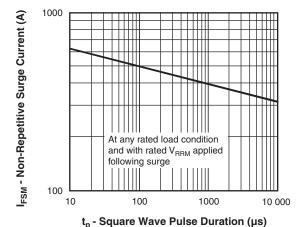


Fig. 7 - Maximum Non-Repetitive Surge Current

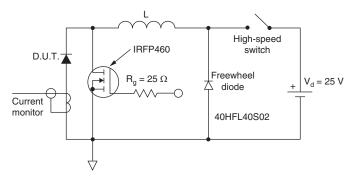


Fig. 8 - Unclamped Inductive Test Circuit

Note

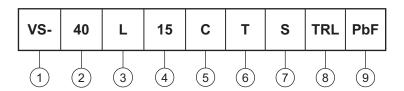
 $^{(1)}$ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = Forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = Inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = 80 % rated V_R

VS-40L15CTSPbF, VS-40L15CT-1PbF

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

Current rating (40 A)

L = Schottky "L" series

Voltage rating (15 V)

- C = common cathode

6 - T = TO-220

5

7 - • S = D²PAK

• -1 = TO-262

8 - • None = tube

• TRL = tape and reel (left oriented - for D²PAK only)

• TRR = tape and reel (right oriented - for D²PAK only)

9 - PbF = lead (Pb)-free

ORDERING INFORMATION (Example)					
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION		
VS-40L15CTSPbF	50	1000	Antistatic plastic tubes		
VS-40L15CTSTRRPbF	800	800	13" diameter plastic tape and reel		
VS-40L15CTSTRLPbF	800	800	13" diameter plastic tape and reel		
VS-40L15CT-1PbF	50	1000	Antistatic plastic tubes		

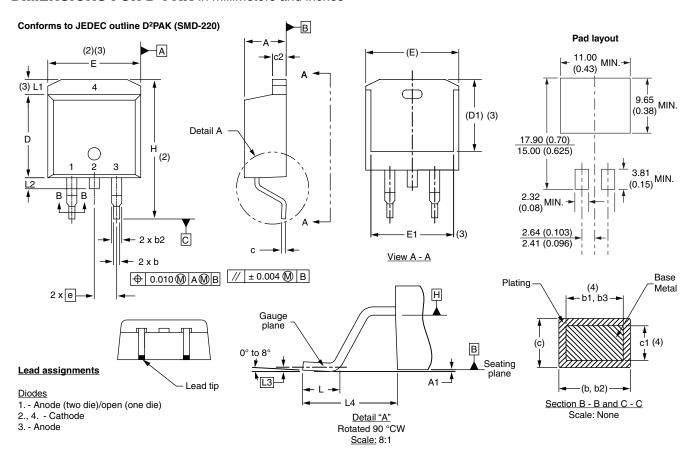
LINKS TO RELATED DOCUMENTS				
Dimensions TO-263AB (D ² PAK) <u>www.vishay.com/doc?95046</u>				
Differsions	TO-262AA	www.vishay.com/doc?95419		
Part marking information		www.vishay.com/doc?95008		
Packaging information		www.vishay.com/doc?95032		



Vishay High Power Products

D²PAK, TO-262

DIMENSIONS FOR D²PAK in millimeters and inches



	MILLIM	MILLIMETERS		INCHES	
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100 BSC		
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25	BSC	0.010	BSC	
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- $^{(3)}\,$ Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch

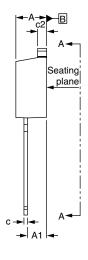
(7) Outline conforms to JEDEC outline TO-263AB

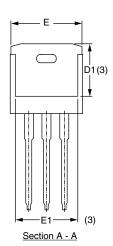
Vishay High Power Products

D²PAK, TO-262



DIMENSIONS FOR TO-262 in millimeters and inches





⊕ 0.010**⋒**|A**⋒**|B

Lead assignments

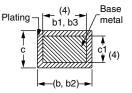


<u>Diodes</u>

-3 x b2 --3 x b

> 1. - Anode (two die)/open (one die) 2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

SYMBOL	MILLIMETERS		INC	INCHES		
	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190		
A1	2.03	3.02	0.080	0.119		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	
D1	6.86	8.00	0.270	0.315	3	
Е	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54 BSC		0.10	0 BSC		
L	13.46	14.10	0.530	0.555		
L1	-	1.65	-	0.065	3	
L2	3.56	3.71	0.140	0.146		

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches

(6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline



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